

Title (en)
CURABLE RESIN COMPOSITION, AND CURED PRODUCT THEREOF

Title (de)
HÄRTBARE HARZZUSAMMENSETZUNG UND GEHÄRTETES PRODUKT DARAUS

Title (fr)
COMPOSITION DE RÉSINE DURCISSABLE ET PRODUIT DURCI CORRESPONDANT

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Abstract (en)
It is an object of the present invention to provide a curable resin composition that forms a cured product having both high heat resistance and toughness. The curable resin composition of the present invention is a curable resin composition comprising a radical polymerizable compound (A), an alicyclic epoxy compound (B), and an acid anhydride (C), or a curable resin composition comprising a radical polymerizable compound (A), an alicyclic epoxy compound (B), and a cationic curing agent (D). These curable resin compositions preferably comprise, as the alicyclic epoxy compound (B), a compound represented by the following formula (b1): wherein X represents a single bond or a linking group (a divalent group comprising one or more atoms).

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Citation (applicant)
JP 2007308683 A 20071129 - HITACHI CHEMICAL CO LTD

Citation (search report)
• [A] WO 2006029095 A1 20060316 - HENKEL CORP [US], et al
• [A] EP 1172393 A1 20020116 - DAICEL CHEM [JP]
• [A] US 2985616 A 19610523 - MCGARY JR CHARLES W, et al

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